ASDM60N45KQ

60V N-Channel MOSFET

General Features

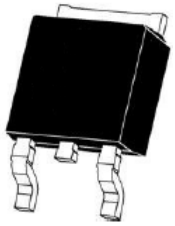
- High density cell design for ultra low Rdson
- Fully characterized avalanche voltage and current
- Good stability and uniformity with high E_{AS}
- Excellent package for good heat dissipation
- Special process technology for high ESD capability

Product Summary

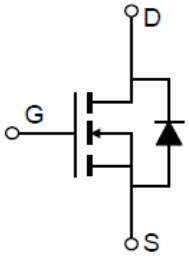
V_{DS}	60	V
$R_{DS(on),Typ}$@ V_{GS}=10 V	12	mΩ
I_D	45	A

Application

- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible Power Supply



TO-252-2L top view



Schematic diagram

Absolute Maximum Ratings (T_C=25℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V_{DS}	60	V
Gate-Source Voltage	V_{GS}	±20	V
Drain Current-Continuous	I_D	45	A
Drain Current-Continuous(T_C=100℃)	I_D(100℃)	35	A
Pulsed Drain Current	I_{DM}	180	A
Maximum Power Dissipation	P_D	80	W
Derating factor		0.53	W/℃
Single pulse avalanche energy (Note 5)	E_{AS}	115	mJ
Operating Junction and Storage Temperature Range	T_J,T_{STG}	-55 To 175	℃

Thermal Characteristics

Parameter	Symbol	Limit	Units
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	2.4	°C/W
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	62	°C/W

Electrical Characteristics (T_C=25℃unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	V_{GS}=0V I_D=250μA	60	-	-	V
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS}=60V,V_{GS}=0V	-	-	1	μA
Gate-Body Leakage Current	I_{GSS}	V_{GS}=±20V,V_{DS}=0V	-	-	±100	nA
On Characteristics (Note 3)						
Gate Threshold Voltage	$V_{GS(th)}$	V_{DS}=V_{GS},I_D=250μA	1.0	1.5	2.5	V
Drain-Source On-State Resistance	$R_{DS(ON)}$	V_{GS}=10V, I_D=20A	-	12	15	mΩ
		V_{GS}=4.5V, I_D=20A	-	14	17	mΩ
Forward Transconductance	g_{FS}	V_{DS}=25V,I_D=20A	24	-	-	S
Dynamic Characteristics (Note4)						
Input Capacitance	C_{lss}	V_{DS}=25V,V_{GS}=0V, F=1.0MHz	-	1920	-	PF
Output Capacitance	C_{oss}		-	221	-	PF
Reverse Transfer Capacitance	C_{rss}		-	70	-	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	$t_{d(on)}$	V_{DD}=30V,I_D=2A,R_L=15Ω V_{GS}=10V,R_G=2.5Ω	-	25	-	nS
Turn-on Rise Time	t_r		-	5	-	nS
Turn-Off Delay Time	$t_{d(off)}$		-	50	-	nS
Turn-Off Fall Time	t_f		-	6	-	nS
Total Gate Charge	Q_g	V_{DS}=30V,I_D=50A, V_{GS}=10V	-	30		nC
Gate-Source Charge	Q_{gs}		-	10		nC
Gate-Drain Charge	Q_{gd}		-	5		nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 3)	V_{SD}	V_{GS}=0V,I_S=40A	-		1.2	V
Diode Forward Current (Note 2)	I_S		-	-	45	A
Reverse Recovery Time	t_{rr}	TJ = 25°C, IF = 40A di/dt = 100A/μs(Note3)	-	50	-	nS
Reverse Recovery Charge	Qrr		-	100	-	nC
Forward Turn-On Time	t_{on}	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)				

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board, t ≤ 10 sec.
3. Pulse Test: Pulse Width ≤ 300μs, Duty Cycle ≤ 2%.
4. Guaranteed by design, not subject to production
5. EAS condition:Tj=25℃,V_{DD}=30V,V_G=10V,L=0.5mH,Rg=25Ω

Typical Electrical and Thermal Characteristics (Curves)

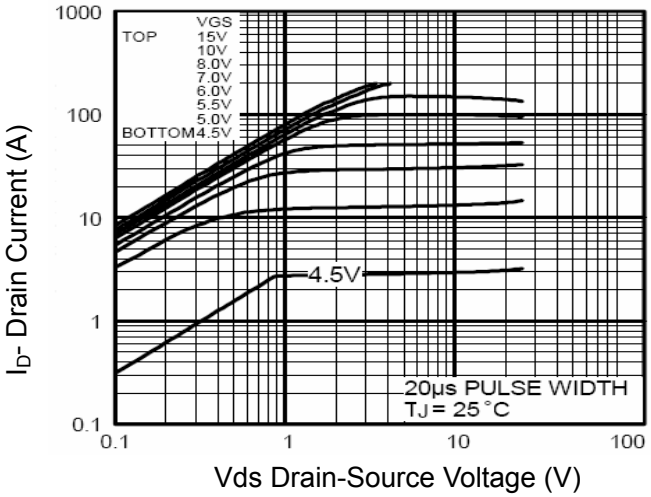


Figure 1 Output Characteristics

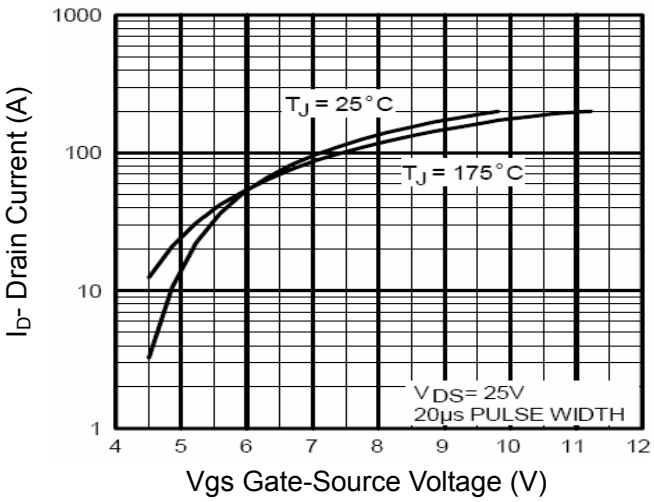


Figure 2 Transfer Characteristics

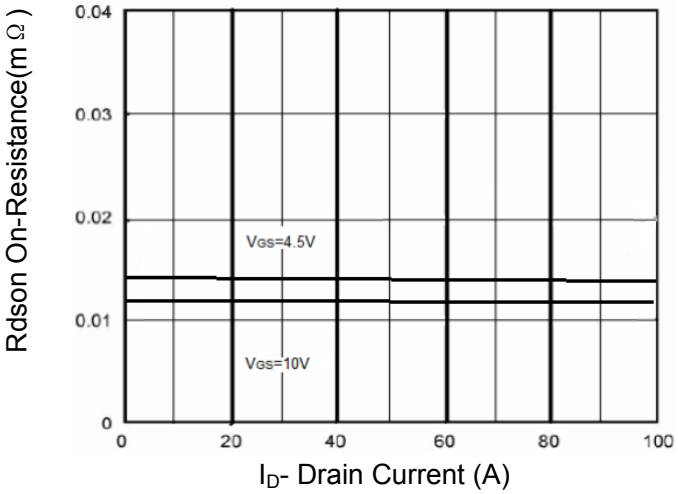


Figure 3 Rdson- Drain Current

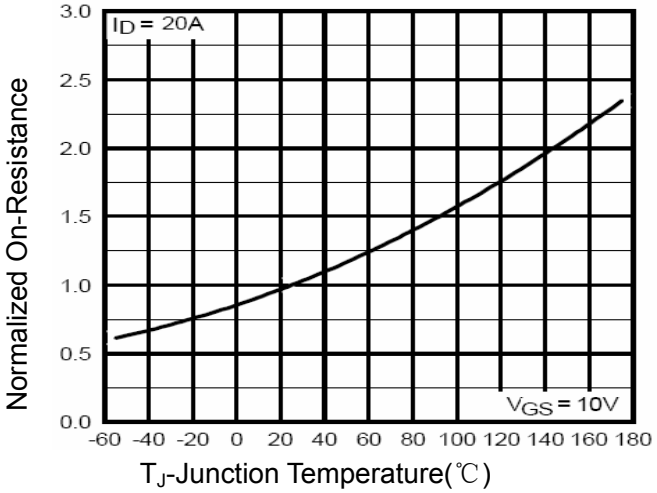


Figure 4 Rdson-Junction Temperature

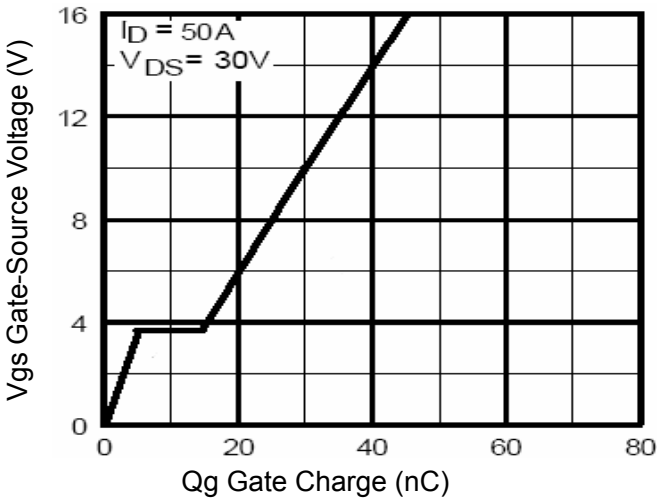


Figure 5 Gate Charge

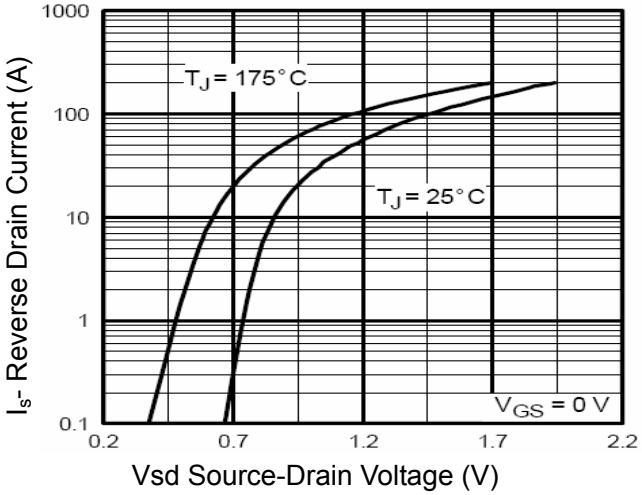


Figure 6 Source- Drain Diode Forward

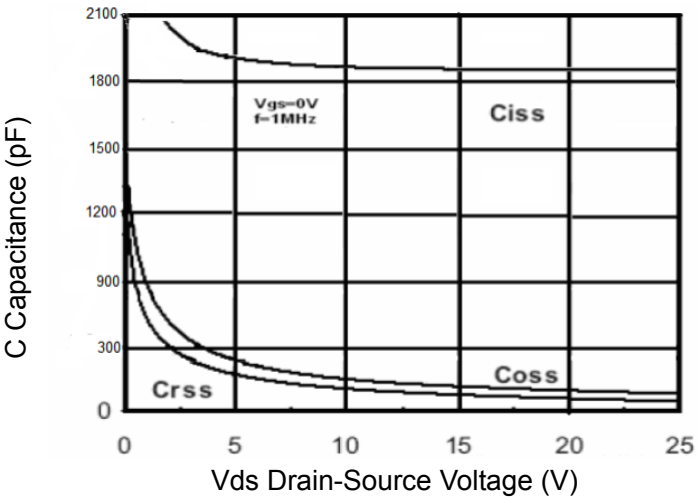


Figure 7 Capacitance vs Vds

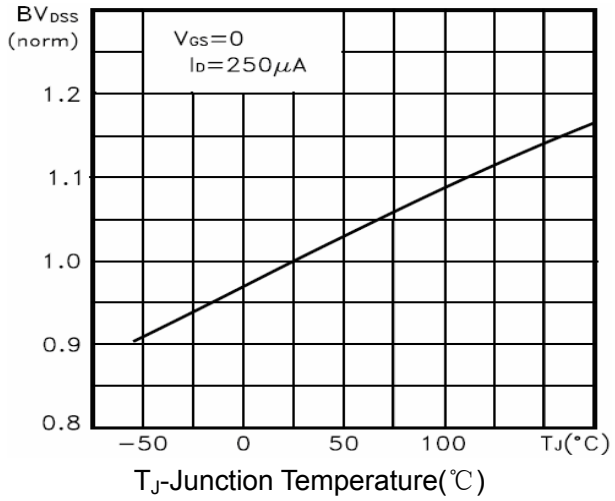


Figure 9 BV_{DSS} vs Junction Temperature

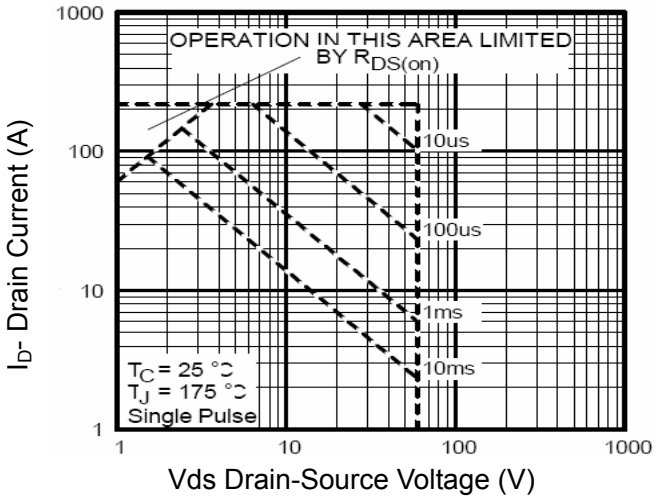


Figure 8 Safe Operation Area

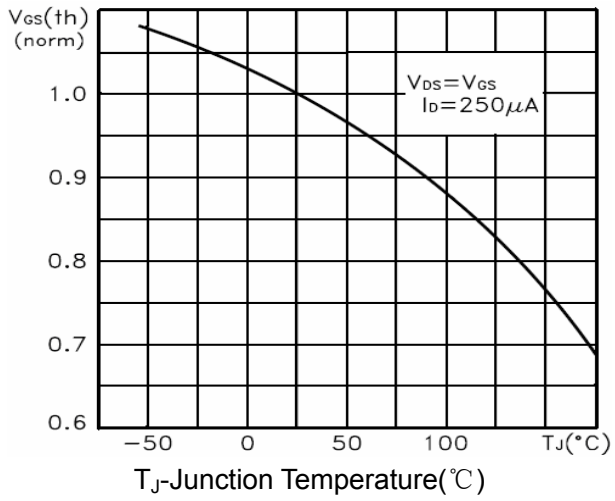


Figure 10 $V_{GS(th)}$ vs Junction Temperature

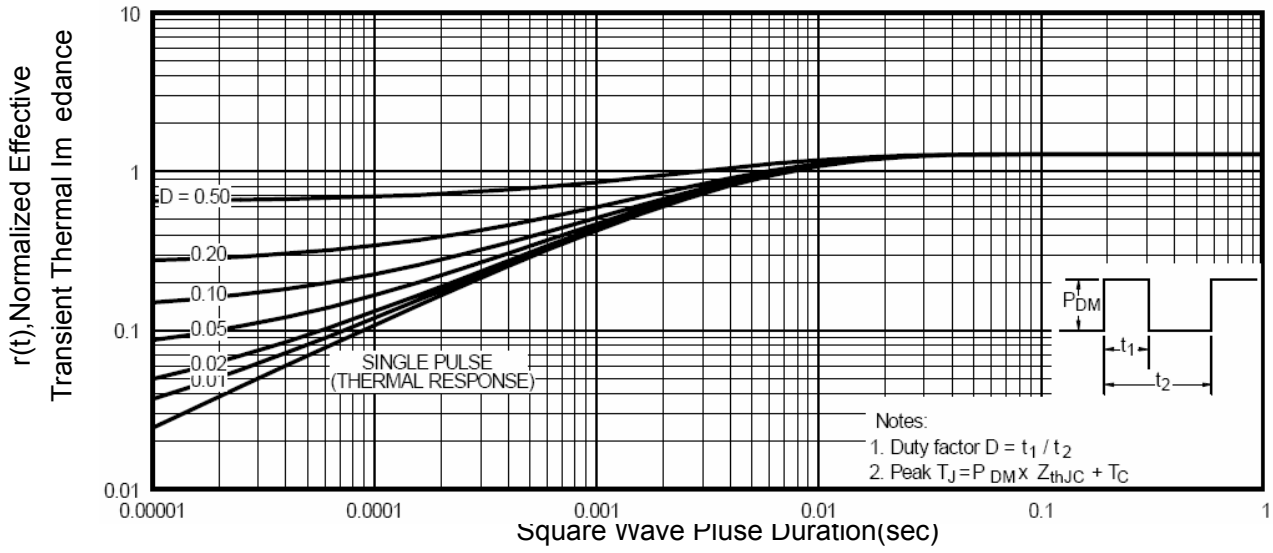
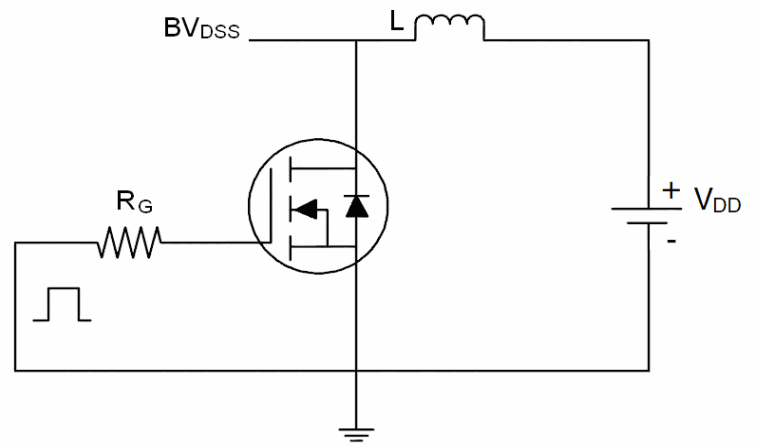


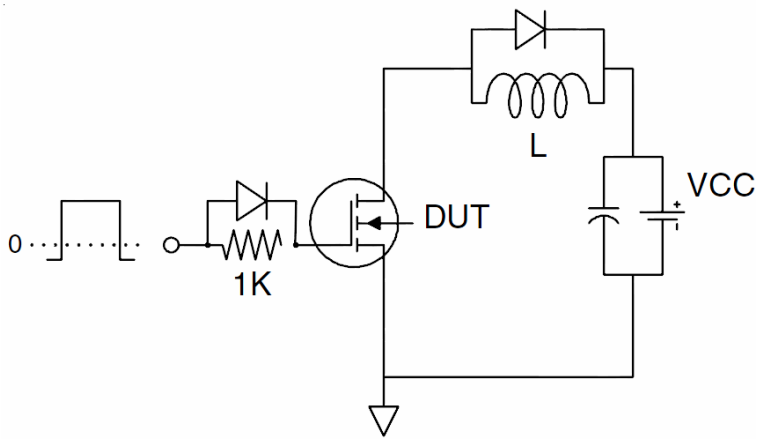
Figure 11 Normalized Maximum Transient Thermal Impedance

Test Circuit

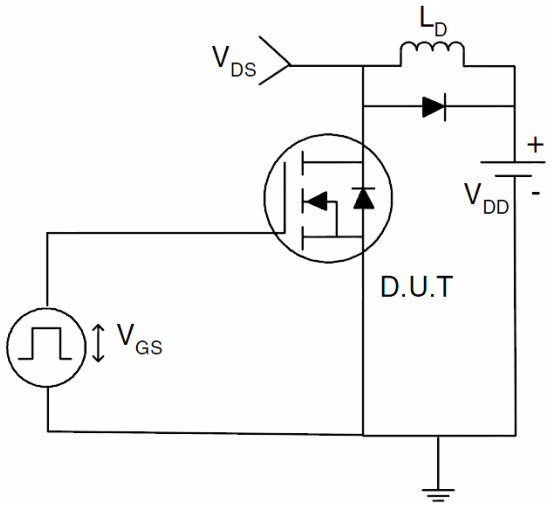
1) E_{AS} Test Circuit



2) Gate Charge Test Circuit

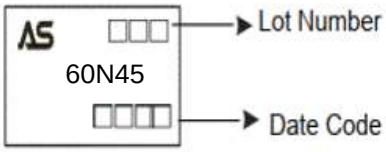


3) Switch Time Test Circuit

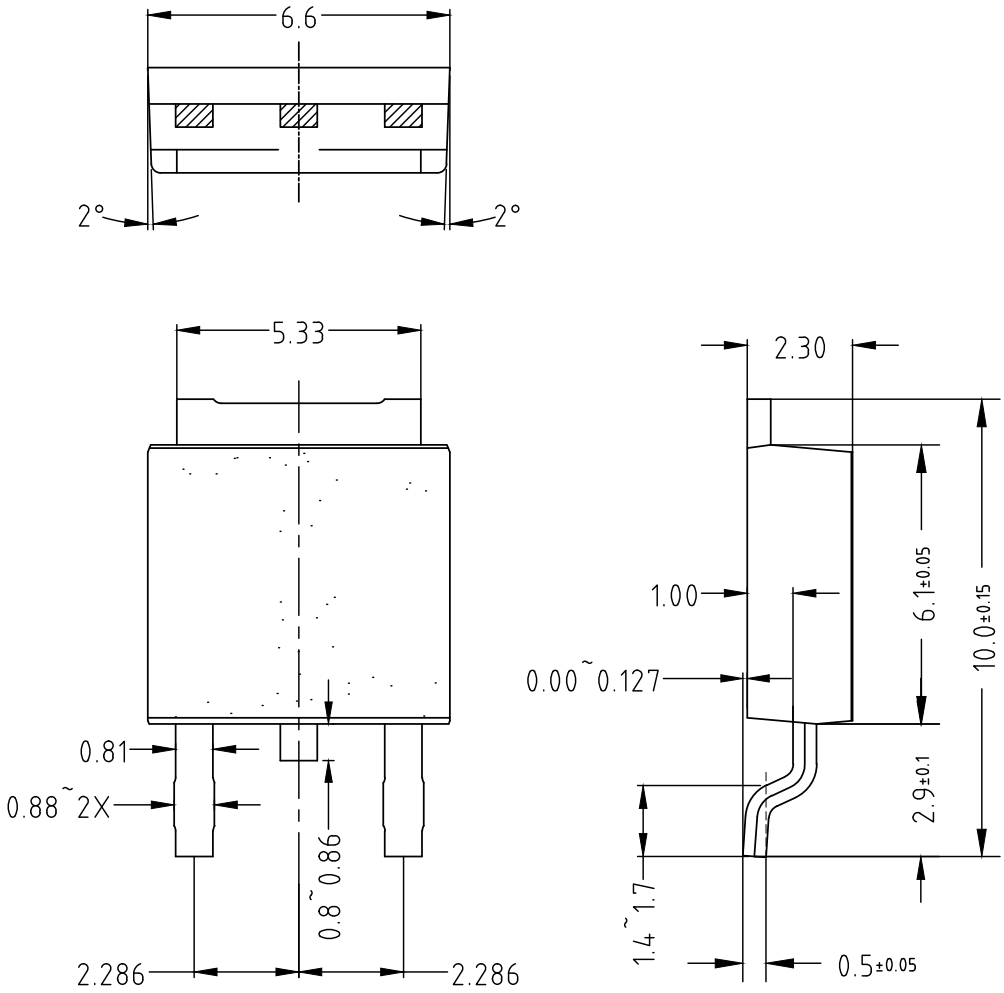


Ordering and Marking Information

Ordering Device No.	Marking	Package	Packing	Quantity
ASDM60N45KQ-R	60N45	TO-252	Tape&Reel	2500/Reel

PACKAGE	MARKING
TO-252	

TO-252


6.6
2°
2°
5.33
0.81
0.88~2X
0.8~0.86
2.286
2.286
2.30
1.00
0.00~0.127
6.1±0.05
10.0±0.15
2.9±0.1
1.4~1.7
0.5±0.05

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